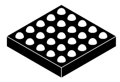
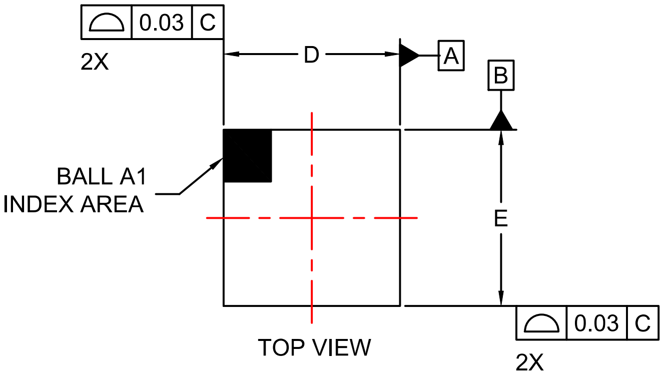


SCALE 4:1

WLCSP25, 2.03x2.03x0.586
CASE 567UP
ISSUE A

DATE 21 MAY 2019

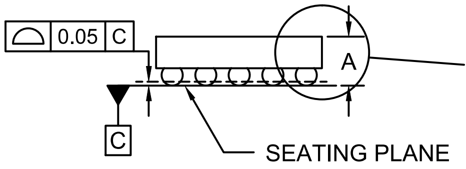


TOP VIEW

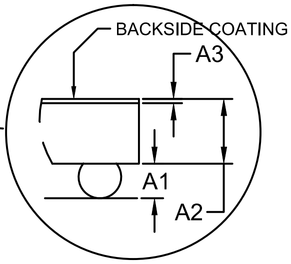
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

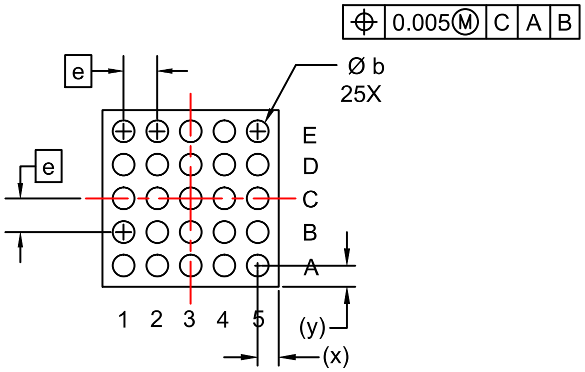
DIM	MIN.	NOM.	MAX.
A	0.547	0.586	0.625
A1	0.188	0.208	0.228
A2	0.337	0.353	0.369
A3	0.022	0.025	0.028
b	0.24	0.26	0.28
D	2.00	2.03	2.06
E	2.00	2.03	2.06
e	0.40 BASIC		
x	0.200	0.215	0.230
y	0.200	0.215	0.230



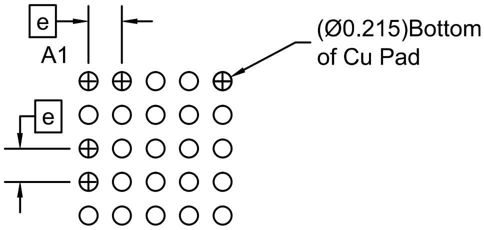
SIDE VIEW



DETAIL A



BOTTOM VIEW



RECOMMENDED
MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	**WLCSP25, 2.03x2.03x0.586**	**PAGE 1 OF 1**